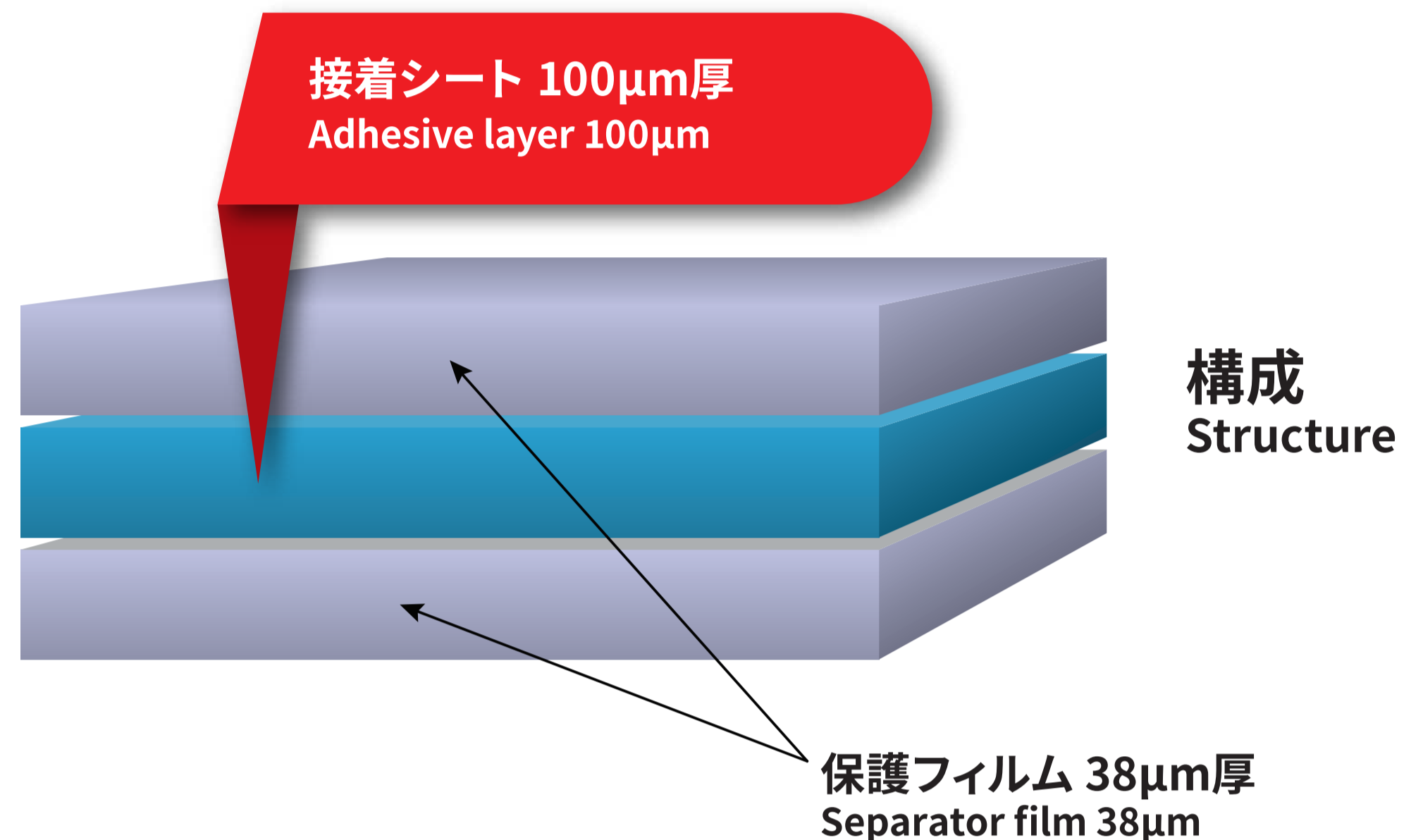


高い電気絶縁性と熱伝導性を両立

High electrical insulation and thermal conductivity

コンセプト Concept



- **絶縁破壊強度: 65kV/mm(AC)、85kV/mm(DC)**

Breakdown voltage AC 65kV/mm, DC 85kV/mm

- **熱伝導率: 3.5W/m・K**

Thermal conductivity 3.5W/m・K

- **ガラス転移点(Tg): 150°C、熱分解開始温度: 300°C**

The glass transition temperature 150°C, Initial temperature for thermal decomposition 300°C

- **高温環境放置後、絶縁破壊電圧の低下無し**

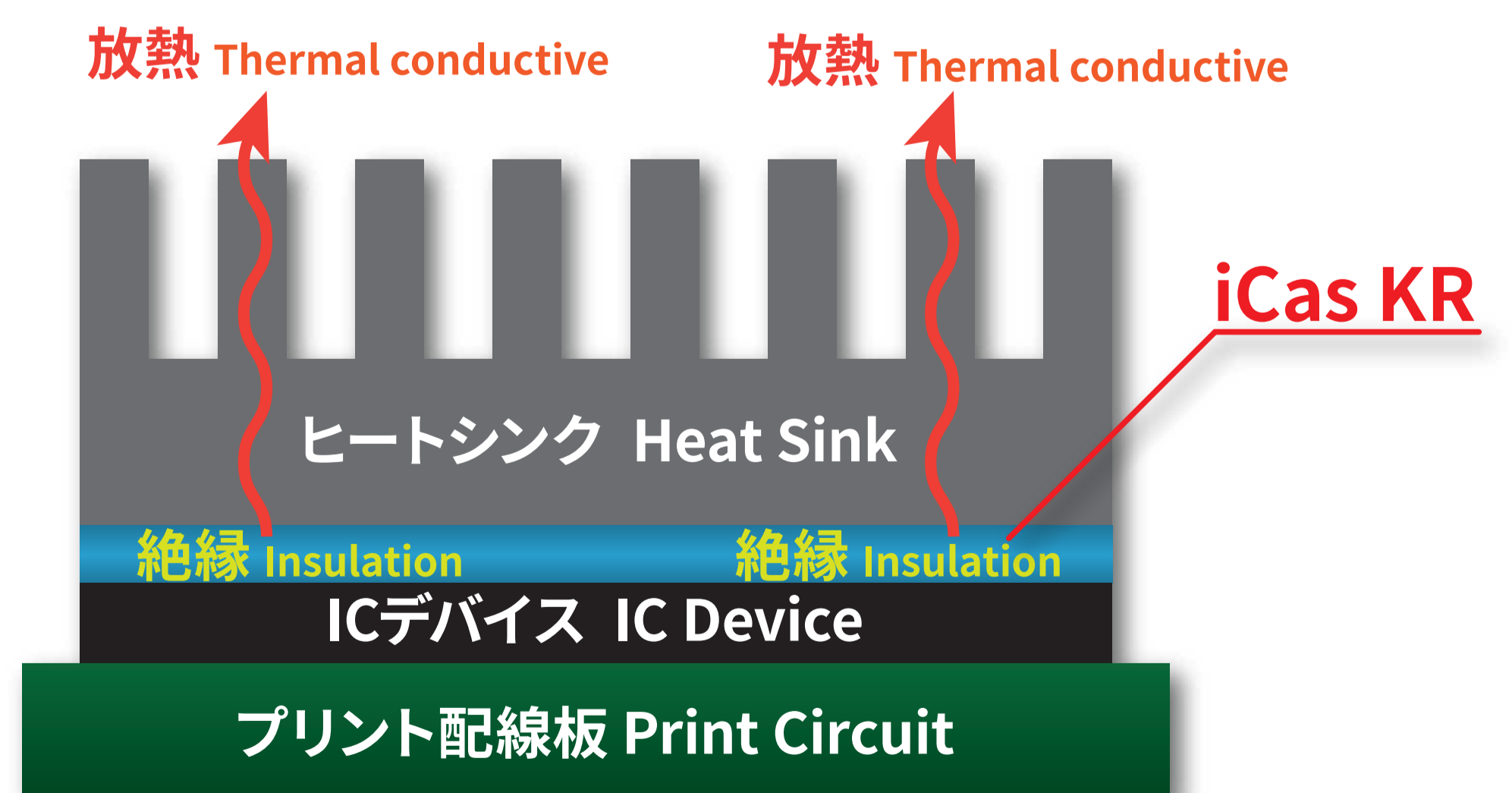
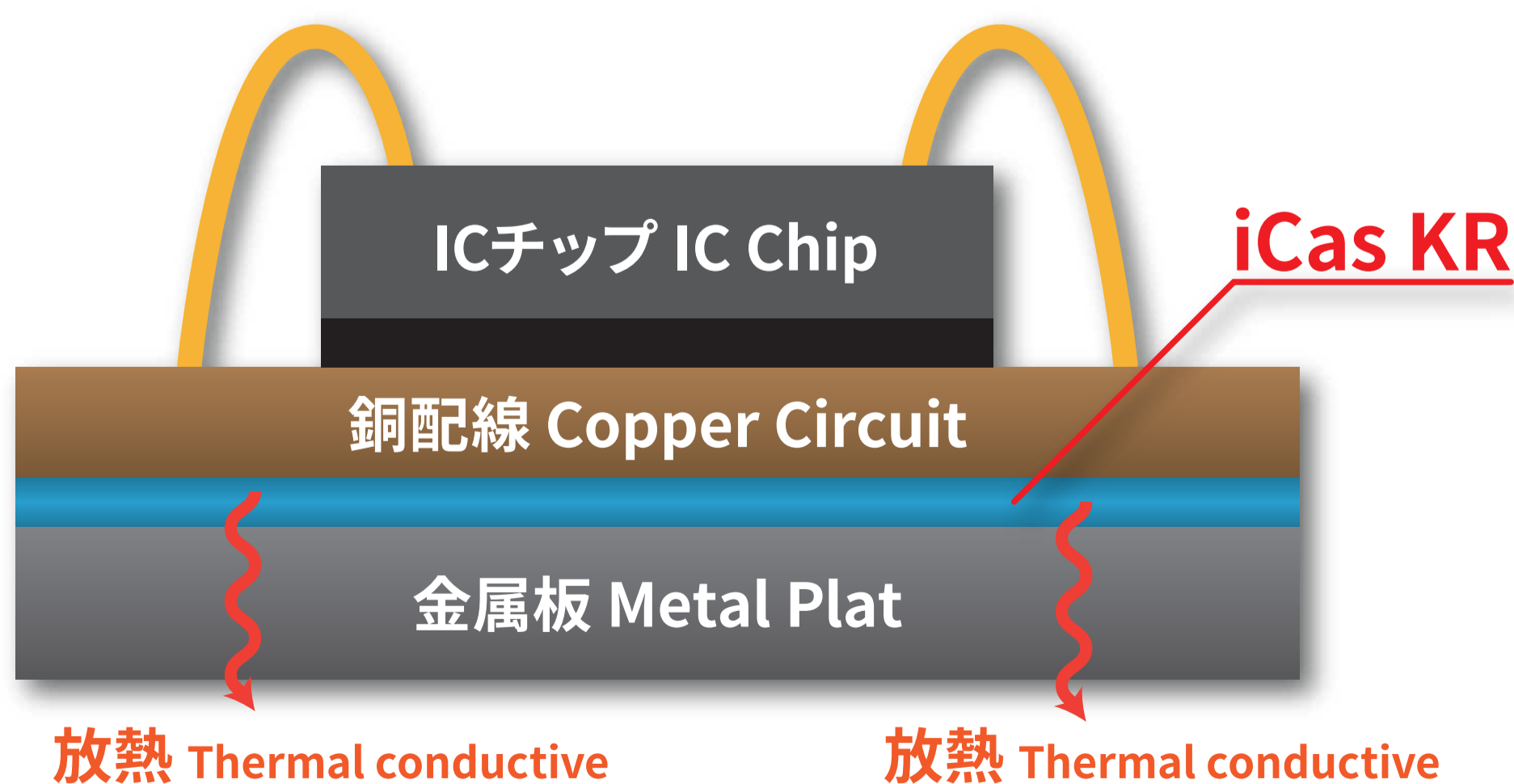
初期: 85kV/mm(DC) → 150°C/1000h後: 87kV/mm(DC)

Ensuring breakdown voltage stability under high temperature environment

Initial: 85kV/mm (DC) ⇒ After 150°C/1000h: 87kV/mm (DC)

※上記数値は代表値であり、保証値ではありません。The data are references, not guaranteed values.

アプリケーション Application



- **ICデバイスと金属部品 (熱伝導部品) との接合**

Joining IC devices with metal parts (heat conductive parts)

